

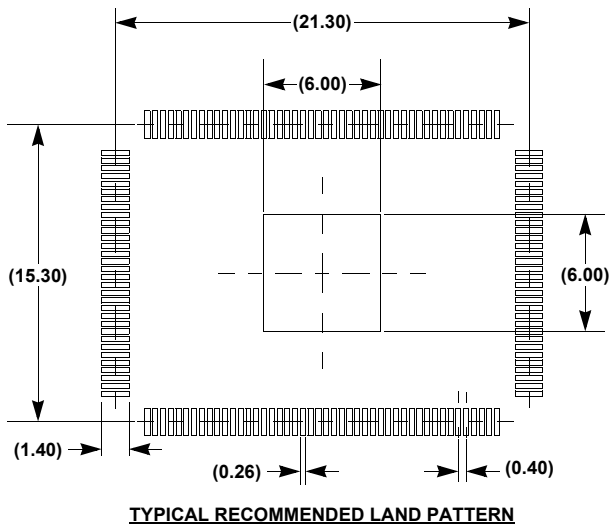
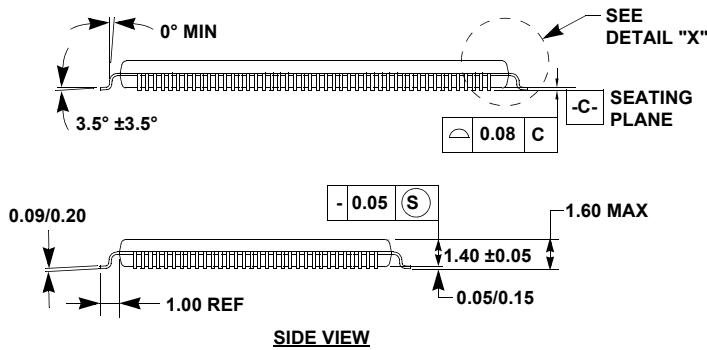
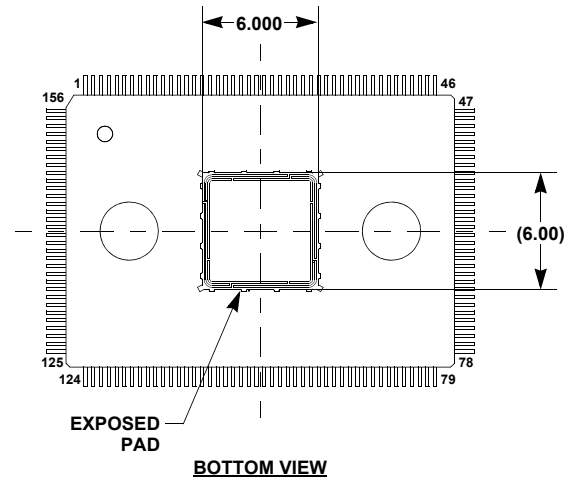
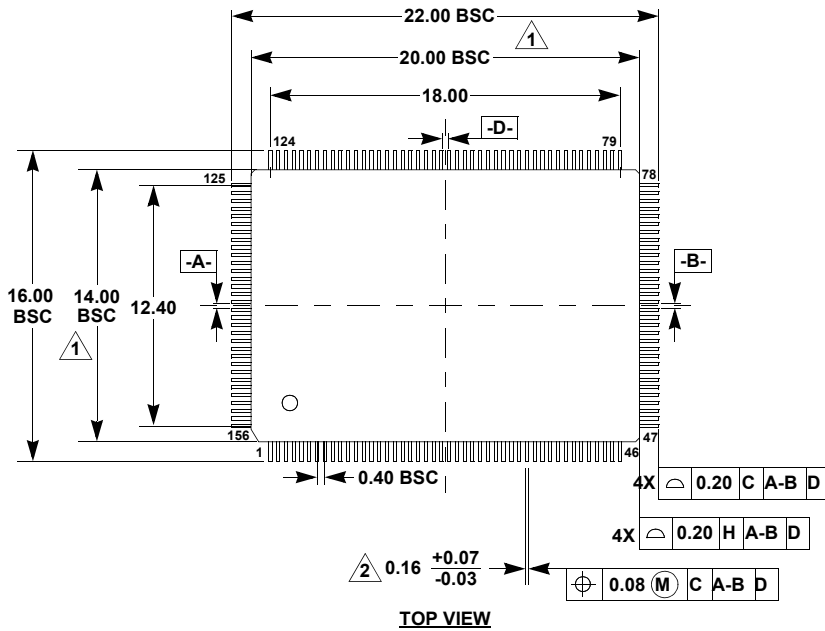
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

Q156.14x20

156 LEAD LOW PLASTIC QUAD FLATPACK EXPOSED PAD PACKAGE (0.4mm LEAD PITCH) (LQFP-EP)

Rev 1, 10/16



**NOTES:**

1. Dimensions do not include mold protrusion.
2. Dimension does not include dambar protrusion. Allowable dambar protrusion shall not cause the lead width to exceed the maximum dimension by more than 0.08mm. Dambar cannot be located on the lower radius or the foot. The minimum space between protrusion and an adjacent lead shall not be less than 0.07mm.
3. The top package body size may be smaller than the bottom package body size.